

**Amendments to the Specification**

Please amend paragraph [01] as follows:

- [01] This application is a continuation of the U.S. Patent Application titled "System and Method for Measurement of Adhesive Resin Distribution on Wood Flakes Using a Scanner," filed on June 26, 2000 and having Serial Number 09/603,995, now U.S. Patent No. 6,618,492, the contents of ~~which is~~which are incorporated by reference herein.